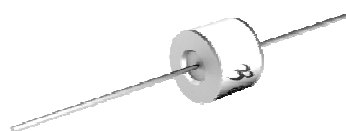


Features

- Size Design $\Phi 8 \times 6\text{mm}$
- High Current Handling Capability 10,000A @ 8/20 μs
- Low Capacitance and Insertion Loss
- Fast Response and Long Service Life
- Reliable to Protect Electrostatic Surge
- Moisture sensitivity level: Level 1

Exterior



Application information

- AC Power

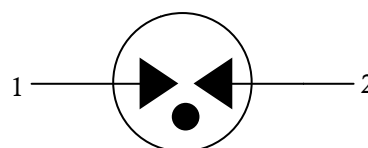
Package (Top View)



Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
UL	Compliance with UL1449, Certificated E337906

Schematic Symbol



Electrical Parameter

DC Breakdown Voltage ^{1) 2)}	100V/s	1200-1800	V
Impulse Spark-over Voltage	At 1kV/ μs	for 99 % of measured values ≤ 2700	V
	At 1kV/ μs	Typical values of distribution ≤ 2500	V
Impulse Discharge Current ³⁾	8/20 μs ± 5 times	10	KA
Arc Voltage	At 1A	~ 15	V
Insulation Resistance	DC=100V	≥ 1	G Ω
Capacitance at 1 MHz	V _{DC} =0.5V	≤ 1.5	pF
Weight		~ 1.62	g
Operating and storage Temperature		-40-90	$^{\circ}\text{C}$
Marking		Bencent Logo, Voltage and date code	

1) At delivery AQL 0.65 level II GB/T 2828.1-2003

2) In ionized mode

3) Terms and current waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

Part Numbering System

B8G XXX M
(1) (2) (3)

(1)Bencent 2-Electrode DIP Gas Discharge Tube with dimension: $\Phi 8.0 \times 6$ (D×L) (mm)

(2) DC Breakdown Voltage, e.g.,600=600V

(3) Surge Rating @8/20 μ s, M=10KA

Product Characteristics

Lead Material	Copper
Body Material	Ceramics Iron-nickel electrode
Terminal Finish	100% Matte-Tin Plated

Environmental Reliability Characteristics

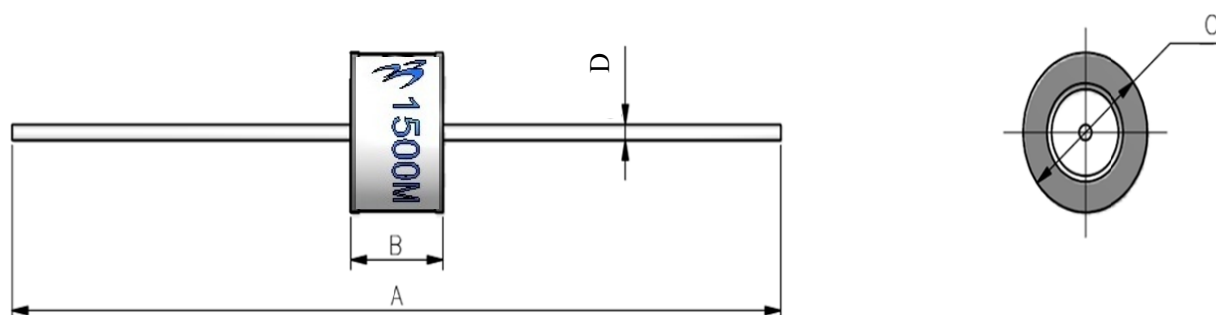
Testing items	Technical standards
High Temperature Storage Test	Temperature: 85℃ Time:2H
Low Temperature Storage Test	Temperature: -40℃ Time:2H
Vibration	Frequency: 10-500Hz Amplitude: 0.15mm Time: 45mins
Resistance of soldering heat	Temperature: 260±5℃ Time of dip soldering: 10s, 1time

Note: Up-screen program can be specified by customer's request via contacting Bencent service

Solderability test

Solderability	Solder Pot Temperature:	245℃ ± 5℃
	Solder Dwell Time:	4-6 seconds

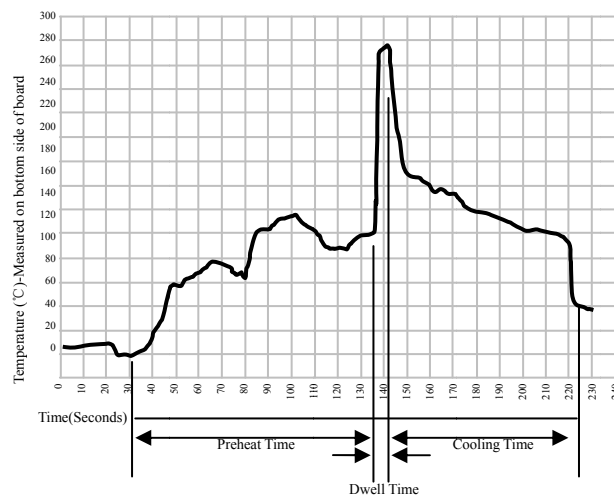
Product Dimensions



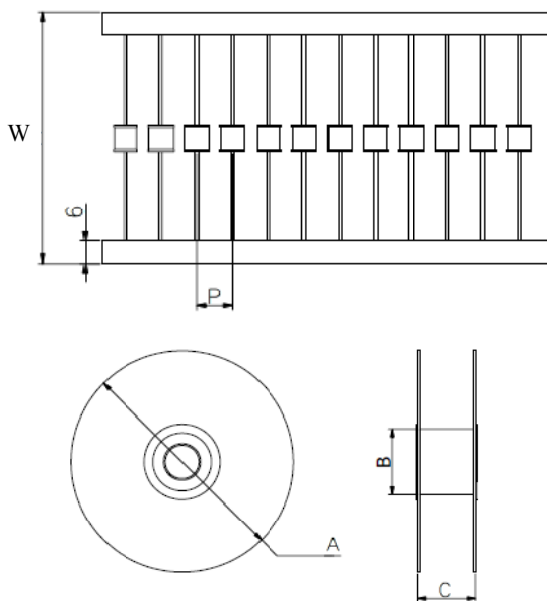
REF	mm	inch
A	62±2	2.441±0.079
B	6±0.2	0.236±0.008
C	$\Phi 8 \pm 0.2$	$\Phi 0.315 \pm 0.008$
D	$\Phi 1.0 \pm 0.06$	$\Phi 0.039 \pm 0.0024$

Wave Soldering profile

Wave Soldering Condition		Pb-Free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time (min to max)	60 – 180 secs
Solder Pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds



Package Reel Information



REF	mm	inch
W	65±3	2.559±0.118
P	10±1	0.394±0.039
A	Φ340±2	Φ13.386±0.079
B	Φ83±2	Φ3.268±0.079
C	73±3	2.874±0.118

OUTLINE	REEL (PCS)	PER CARTON (PCS)	CARTON SIZE(mm)		
			L	W	H
TAPING	700	4200	480	350	360